ABSTRACT OF THE DISCLOSURE

A shielding layer 14 is formed onto the circuit device 10. The backface of a conductive pattern 11 is exposed, and a shielding layer 14 made of a metal, such as copper, is formed on the upper surface of an insulating resin 13 with which a circuit element 12, a fine metal wire 16, and a conductive pattern 11 are covered. A connecting means 15 is formed on a through-hole 20 formed by removing a part of the insulating resin 13. The shielding layer 14 and the conductive pattern 11B are electrically connected together through the connecting means 15. Since the conductive pattern 11B at the part where the through-hole 20 is formed is a conductive pattern serving as an ground potential, the shielding layer 14 can be set at zero potential.